

LIST OF IPC SPECIFICATIONS AVAILABLE WITH IPCA

LIST OF IPC,USA, SPECIFICATIONS AVAILABLE WITH IPCA

FOR REFERENCE

CODE	DESCRIPTION

S-100.	STANDARDS & SPECIFICATIONS MANUAL
1902.	IPC/IEC GRID SYSTEMS FOR PRINTED CIRCUITS
2221.	GENERIC STANDARD ON PRINTED BOARD DESIGN AMEND-1
2222.	SECTIONAL STANDARD ON RIGID PWB DESIGN
2223.	SECTIONAL DESIGN STANDARD FOR FLEXIBLE PRINTED BOARDS
2224.	SECTIONAL STANDARD OF DESIGN OF PBW FOR PC CARDS
2225.	SECTIONAL DESIGN STANDARD FOR ORGANIC MULTICHIP MODULES (MCM-L) AND MCM-L ASSEMBLIES
2226.	GENERIC REQUIREMENTS FOR IMPLEMENTAION OF PRODUCT MANUFACTURING DESCRIPTION DATA AND TRANSFER METHODOLGY
2524.	PWB FABRICATION DATA QUALITY RATING SYSTEM
2615.	PRINTED BOARD DIMENSIONS AND TOLERANCES
3406.	GUIDELINES FOR ELECTRICALLY CONDUCTIVE SURFACE MOUNT ADHESIVES
3408.	GENERAL REQUIREMENTS FOR ANISOTROPICALLY CONDUCTIVE ADHESIVES
4101.	SPECIFICATIONS FOR BASE MATERIALS FOR RIIGID BOARD AND MULTILAYER PRINTED BOARDS
4104.	SPECIFICATIONS FOR HIGH DENSITY INTERCONNECT (HDI) AND MICROVIA MATERIALS
4110.	SPECIFICATIONS & CHARACTERIZATION METHODS FOR NON WOVEN CELLULOSE BASED PAPER FOR PRINTED BOARDS
4130.	SPECIFICATION AND CHARACTERIZATION METHODS FOR NONWOVEN "E" GLASS MAT
4411.	SPECIFICATION AND CHARACTERIZATION METHODS FOR NONWOVEN PARA-ARMID REINFORCEMENT
4562.	METAL FOIL FOR PRINTED WIRING APPLICATIONS
6011.	GENERIC PERFORMANCE SPECIFICATION FOR PRINTED BOARDS
6012A	"DO NOT USE" USE 6012m-AM INSTEAD & AM
6013.	QUALIFICATION & PERFORMANCE SPECIFICATION FOR FLEXIBLE PRINTED BOARDS

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6013-A1 QUALIFICATION & PERFORMANCE SPECIFICATION FOR FLEXIBLE PRINTED BOARDS AMEND.1

6015. QUALIFICATION & PERFORMANCE FOR ORGANIC MULTICHIP MODULE (MCM-L) MOUNTING AND INTERCONNECTING STRUCTURES

6016. QUALIFICATION & PERFORMANCE SPECIFICATION FOR HIGH DENSITY INTERCONNECT (HDI) LAYERS OR BOARDS

6018. MICROWAVE END PRODUCT BOARD INSPECTION AND TEST

6202. IPC/JPCA PERFORMANCE GUIDE MANUAL FOR SINGLE AND DOUBLE SIDED FLEXIBLE PRINTED WIRING BOARDS

A-142 SPECIFICATION FOR FINISHED FABRIC WOVEN FROM ARAMID FOR PRINTED BOARDS

BP-421 GENERAL SPECIFICATION FOR RIGID PRINTED BOARD BACKPLANES WITH PRESS-FIT CONTACTS

CA-821 GENERAL REQUIREMENTS FOR THERMALLY CONDUCTIVE ADHESIVES

CF-148A RESIN COATED METAL FOR PRINTED BOARDS

CF-152B COMPOSITE METALLIC MATERIALS SPECIFICATION FOR PRINTED WIRING BOARDS

D-322 GUIDELINES FOR SELECTING PRINTED WIRING BOARD SIZES USING STANDARD PANEL SIZES

D-325A DOCUMENTATION REQUIREMENTS FOR PRINTED BOARDS

D-326 INFORMATION REQUIREMENTS FOR MANUFACTURING ELECTRONIC ASSEMBLIES

D-356A BARE BOARD ELECTRICAL TEST INFORMATION IN DIGITAL FORM

D-859 DESIGN STANDARD FOR THICK FILM MULTILAYER HYBRID CIRCUITS

DD-135 QUALIFICATION FOR DEPOSITED ORGANIC INTERLAYER DIELECTRIC MATERIALS FOR MULTICHIP MODULES

DR-570A GENERAL SPECIFICATION FOR 1/8 INCH DIAMETER SHANK CARBIDE DRILLS FOR PRINTED BOARDS

DW-424 GENERAL SPECIFICATION FOR ENCAPSULATED DISCRETE WIRE INTERCONNECTION BOARDS

DW-425A DESIGN AND END PRODUCT REQUIREMENTS FOR DISCRETE WIRING BOARDS

DW-426 SPECIFICATIONS FOR ASSEMBLY OF DISCRETE WIRING

EG-140 SPECIFICATION FOR FINISHED FABRIC WOVEN FROM "E" GLASS FOR PRINTED BOARD

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FC-231C FLEXIBLE BARE DIELECTRICS FOR USE IN FLEXIBLE PRINTED WIRING

FC-232C SPECIFICATION FOR ADHESIVE COATED DIELECTRIC FILMS FOR USE AS
COVERSHEETS FOR FLEXIBLE PRINTED WIRING

FC-241C FLEXIBLE METAL-CLAD DIELECTRICS FOR USE IN FABRICATION OF FLEXIBLE
PRINTED WIRING

HM-860 SPECIFICATION FOR MULTILAYER HYBRID CIRCUITS

J-STD-001C REQUIREMENTS FOR SOLDERED ELECTRICAL AND ELECTRONIC ASSEMBLIES

J-STD-002A SOLDERABILITY TESTS FOR COMPONENT LEADS, TERMINATIONS, LUGS,
TERMINALS AND WIRES

J-STD-003 SOLDERABILITY TESTS FOR PRINTED BOARDS

J-STD-004 REQUIREMENTS FOR SOLDERING FLUXES – INCLUDES AMENDMENT-1

J-STD-005 REQUIREMENTS FOR SOLDERING PASTES-INCLUDES AMENDMENT 1

J-STD-006 REQUIREMENTS FOR ELECTRONIC GRADE SOLDER ALLOYS AND FLUXED &
NON-FLUXED SOLID SOLDERS FOR ELECTRONIC SOLDERING APPLICATIONS – INCLUDES

J-STD-020A MOISTURE/REFLOW SENSITIVITY CLASSIFICATION FOR NON-HERMETIC SOLID
STATE SURFACE MOUNT DEVICES

J-STD-033 STANDARD FOR HANDLING PACKING, SHIPPING AND USE OF
MOISTURE/REFLOW SENSITIVE SURFACE MOUNT DEVICES

L-125A SPECIFICATION FOR PLASTIC SUBSTRATES, CLAD OR UNCLAD, FOR HIGH
SPEED/HIGH FREQUENCY INTERCONNECTIONS

MC-324 PERFORMANCE SPECIFICATION FOR METAL CORE BOARDS

ML-960 QUALIFICATION AND PERFORMANCE SPECIFICATION FOR MASS LAMINATION
PANELS FOR MULTILAYER PRINTED BOARDS

NC-349 COMPUTER NUMERICAL CONTROL FORMATTING FOR DRILLERS AND ROUTERS

645. STANDARD FOR VISUAL OPTICAL INSPECTION AIDS

QF-143 SPECIFICATIONS FOR FINISHED FABRIC WOVEN FROM QUARTZ (PURE FUSED
SILICA) FOR PRINTED BOARDS

QL-653A QUALIFICATION OF FACILITIES THAT INSPECT/TEST PRINTED BOARDS,
COMPONENTS AND MATERIALS

SG-141 SPECIFICATION FOR FINISHED FABRIC WOVEN FROM "S" GLASS FOR PRINTED
BOARDS

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SM-840C QUALIFICATION AND PERFORMANCE OF PERMANENT SOLDER MASK INCLUDES AMEND 1

T-50F TERMS AND DEFINITIONS FOR INTERCONNECTING AND PACKAGING ELECTRONIC CIRCUITS

TF-870 QUALIFICATION AND PERFORMANCE OF POLYMER THICK FILM PRINTED BOARDS

A-600F ACCEPTABILITY OF PRINTED BOARDS

TM-650 TEST METHODS MANUAL

TM-650-S TEST METHODS MANUAL – 2 YEAR UPDATING SERVICE (SUBSCRIPTION)

6011. GENERIC PERFORMANCE SPECIFICATION FOR PRINTED BOARDS

6012A-AM QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARDS – INCLUDES AMEND 1